

Date: 13 Oct 2023

Mid-semester Test (Closed Book) FN1

Max. Marks: 75

General Instructions to the candidate

- Please write your answers legibly and neatly in the answer booklet provided only.
- Symbols, constants, terminology used have their usual meaning unless specified specially.
- There are a total of **Four** questions, and all are compulsory. Each carries marks as indicated.

Unless specifically mentioned—

Common data: Use the following common data (250nm technology) if not mentioned specifically in the question

Take $V_{DD}=2.5$ V, $L_{min}=W_{min}=250$ nm, $R_{nmos}=13$ kohm/ unit (W/L), $R_{pmos}=31$ kohm/ unit (W/L),

$V_{TON}=0.4$ V, $V_{TOP}=-0.4$ V, $\lambda_n=0.1$ V⁻¹, $\lambda_p=0.1$ V⁻¹, $\mu_n C_{ox}=120$ uA/ V², $\mu_p C_{ox}=40$ uA/ V²

- Use **square law current equation** unless specifically mentioned. Use lambda based design rules unless specially mentioned.
- Neglect body effect, channel length modulation if not mentioned specifically.
- The body of all PMOS is tied to V_{DD} while all NMOS is tied to ground unless specially mentioned.
- Label your sketches properly.

Answer all the subparts of a question together in sequence.

Q1. Consider the design of a CMOS circuit in 90 nm technology node to implement the Boolean function appended below:

$$F = \overline{(A + B)(C + D)}$$

- Sketch and label its transistor-level schematic.
- Hence, find all the possible Euler's path.
- Hence, sketch and label its stick diagram for Euler's path ABCD.
- Estimate the cell area from stick diagram.
- Hence, sketch and label the cross-sectional diagram across p-diffusion region.

[20 marks]

Q2. The layout of a PMOS is given in Fig.1. Use the parameters given in this question.

$V_{TOP} = -1$ V, $K'_p = 20$ uA/V², $C_{ox} = 69$ nF/cm², $C_{jsw} = 2.2$ pF/cm, $C_{jo} = 7$ nF/cm², $K_{eq,p} = 0.5$ (for all kind of junctions), $L_D = 1$ u μ m, $W = 10$ u μ m, $P = 14$ u μ m, $Q = 6$ u μ m, $R = 8$ u μ m,

$x_j = 32$ nm, $t_{ox} = 1.5$ nm, $L_{mask}=5$ um

- Calculate value of gate (C_{gb}), drain (C_{gd}) and source (C_{gs}) oxide capacitances when MOS is in linear and saturation region of operations, respectively.

- b) Calculate total junction capacitance of the device (source + drain region) under the state of thermal equilibrium. (Assume **No conduction** in the channel and No external bias is applied at any of the terminals of the PMOS)
- c) Now calculate the total junction capacitance (source + drain region) when device is operating in linear region with a swing from 0- V_{DD} .

[15 marks]

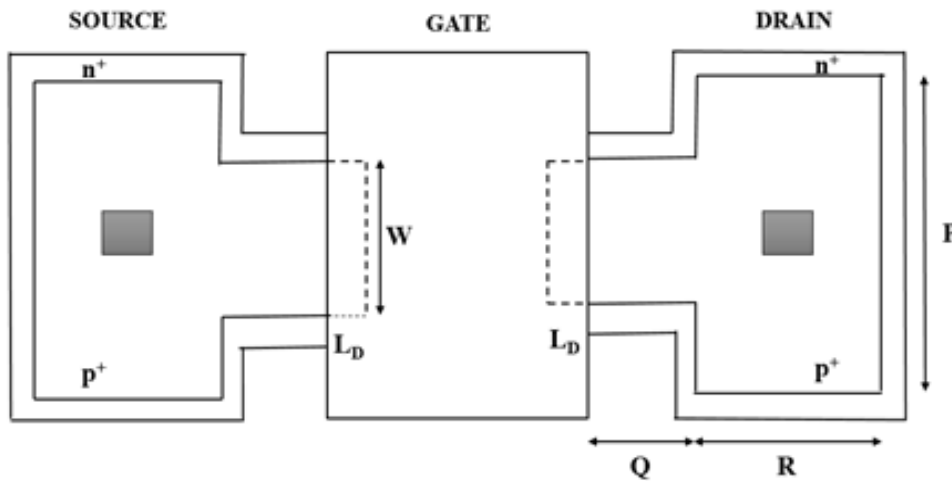


Fig. 1

Q3. Consider the CMOS inverter schematic shown in the Fig. 2.

Ignore channel length modulation, body bias effect, and parasitic capacitances

All transistors have the same ON resistance 'R' and $N_{MH} = N_{ML}$. The V_{out} value corresponding to

V_{IH} is **0.5V**

- a) Determine the values of V_M , V_{IL} , V_{IH} , N_{ML} , N_{MH} .
- b) Now, assume all NMOS transistors become fast by **20%**, and all PMOS transistors become slow by **20%**. Determine the new values of V_M , V_{IL} , V_{IH} .

Here, assume the same V_{out} values for V_{IL} and V_{IH} as in part

(a).

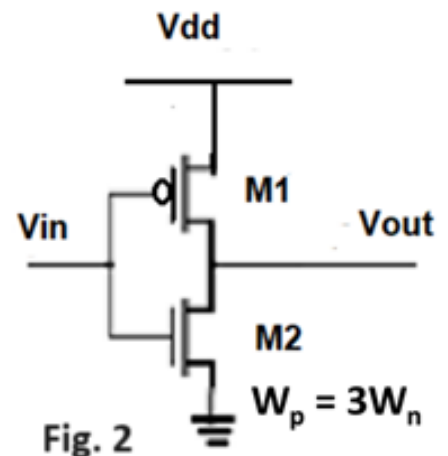


Fig. 2

[20 marks]

Q4. Consider circuit shown in Fig. 3, Given that node labeled as 'X', has total capacitance value $C_x=20$ fF. The transistor sizes are given as ----:

$$(W/L)_{M1}=(W/L)_{M2}=(W/L)_{M3} = 3$$

$$(W/L)_{M4} = 3 \quad [\text{P-Tree is a complement of N-Tree}]$$

where each PMOS device has same aspect ratio of $(W/L)_{M4}$

a) Derive and calculate value fall time " τ_{fall} " at node 'X' (here take V_{DD} to 10 % of V_{DD}). (Assume the default device parameters mentioned at start and ideal step inputs. [Use differential equation based formula/method for all the delay calculation])

b) Hence, calculate maximum short circuit power consumption of first stage of Fig. 3. Assume , for input waveform, ' τ_{fall} ' = ' τ_{rise} ' and has same value as calculated in part (a)] . Given input frequency is 1 MHz.

[20 marks]

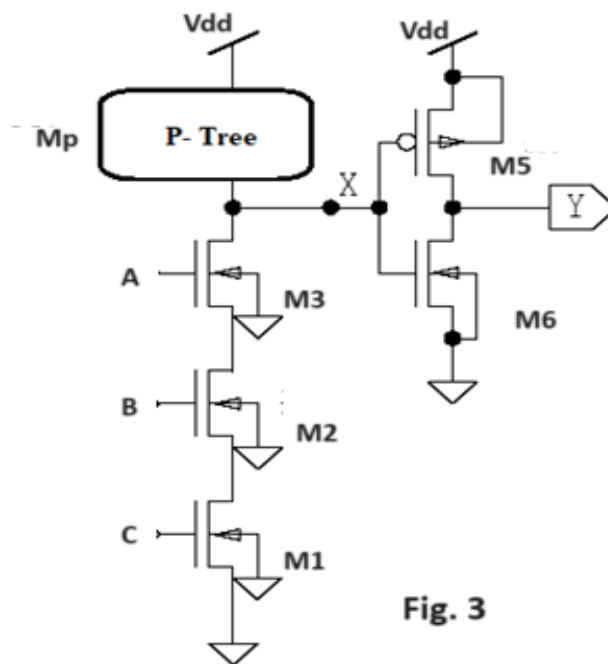


Fig. 3

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